

AMENDMENTS TO THE CLAIMS

1. (Currently Amended) A suspension bonding pad ~~for electrically bonding to electrically bond~~ a magnetic head terminal comprising a metal pad having a bonding substance applied as a surface finishing material, the surface finishing material being heat treated prior to bonding to a surface.
2. (Currently Amended) A suspension bonding pad ~~for electrically bonding to electrically bond~~ a magnetic head terminal as set forth in claim 1, wherein said bonding substance is solder.
3. (Currently Amended) A suspension bonding pad ~~for electrically bonding to electrically bond~~ a magnetic head terminal as set forth in claim 1, wherein said bonding substance is a conductive polymer.
4. (Currently Amended) A suspension bonding pad ~~for electrically bonding to electrically bond~~ a magnetic head terminal as set forth in claim 1, wherein said bonding substance is an adhesive.
5. (Currently Amended) A suspension bonding pad ~~for electrically bonding to electrically bond~~ a magnetic head terminal as set forth in claim 1, wherein said bonding substance is a film.

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6. (Currently Amended) A suspension bonding pad for electrically bonding to electrically bond a magnetic head terminal as set forth in claim 2, wherein a bump height for the solder is approximately 50-300 μm , and a bump diameter for the solder is less than 180 μm .

7. (Currently Amended) A disk drive suspension comprising:
a bonding pad for electrically bonding a magnetic head terminal, wherein said bonding pad includes a metal pad having a bonding substance applied as a surface finishing material, the surface finishing material being heat treated prior to bonding to a surface.

8. (Currently Amended) The disk drive suspension as claim set forth in claim 7, wherein said bonding substance is solder.

9. (Currently Amended) The disk drive suspension as claim set forth in claim 7, wherein said bonding substance is a conductive polymer.

10. (Currently Amended) The disk drive suspension as claim set forth in claim 7, wherein said bonding substance is an adhesive.

11. (Currently Amended) The disk drive suspension as claim set forth in claim 7, wherein said bonding substance is a film.

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12. (Currently Amended) The disk drive suspension as claim set forth in claim 8, wherein a bump height for the solder is approximately 50-300 μm , and a bump diameter for the solder is less than 180 μm .
